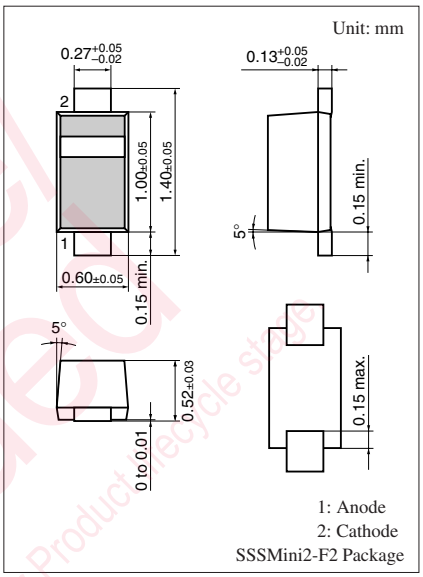
MA27P02

Silicon epitaxial planar type

For high frequency switch



Marking Symbol: Y

■ Features

- Small terminal capacitance C_t
- Small forward dynamic resistance r_f
- Ultraminiature package and surface mounting type 1.0 mm × 0.6 mm (height: 0.52 mm)

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	60	V
Forward current	I_F	100	mA
Power dissipation *	P_D	150	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

Note) *: With a glass epoxy PC board

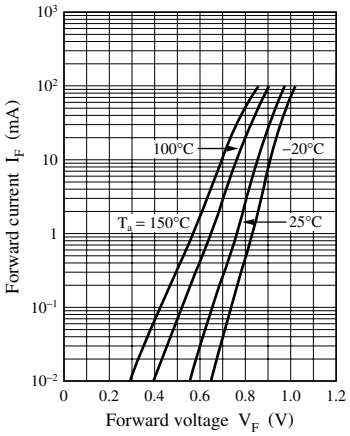
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 10 mA			1.0	V
Reverse current	I_R	V_R = 60 V			100	nA
Terminal capacitance	C_t	V_R = 1 V, f = 1 MHz			0.5	pF
Forward dynamic resistance *	r_f	I_F = 10 mA, f = 100 MHz			2.0	Ω

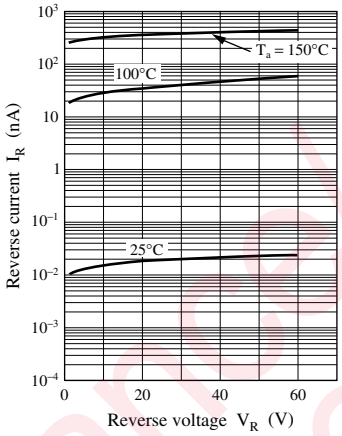
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. *: r_f measurement device ; agilent model 4291B

Maintenance/Discontinued
Maintenance/Discontinued includes following four Product lifecycle stage
planned maintenance type
maintenance type
planned discontinued typed
discontinued type
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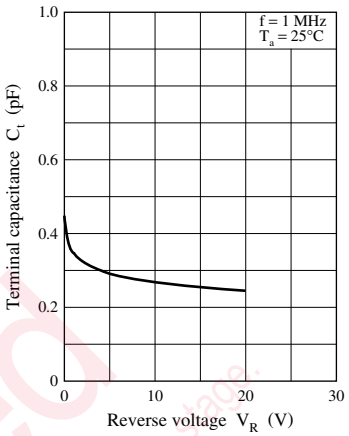
I_F — V_F



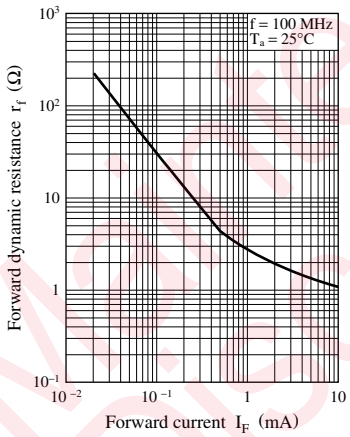
I_R — V_R



C_t — V_R



r_f — I_F



Maintenance/Discontinued
Discontinued includes following four Product lifecycle stage.
planed maintenance type
maintenance type
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